

RoHS

COMPLIANT

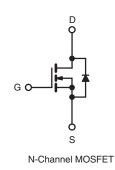
N-Channel 60 V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	60					
R _{DS(on)} (Ω)	$V_{GS} = 10 V$	0.027				
Q _g (Max.) (nC)	95					
Q _{gs} (nC)	27					
Q _{gd} (nC)	46					
Configuration	Single					

FEATURES

- · Isolated Package
- High Voltage Isolation = 2.5 kV_{RMS} (t = 60 s; f = 60 Hz)
- Sink to Lead Creepage Distance = 4.8 mm
- 175 °C Operating Temperature
- · Dynamic dV/dt Rating
- · Low Thermal Resistance
- Lead (Pb)-free Available





ABSOLUTE MAXIMUM RATINGS T	_C = 25 °C, u	nless otherv	vise noted			
PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-Source Voltage			V _{DS}	60	v	
Gate-Source Voltage			V _{GS}	± 20	v	
Continuous Drain Current	V _{GS} at 10 V	T _C = 25 °C	- I _D	45		
	VGS at 10 V	T _C = 100 °C		30	А	
Pulsed Drain Current ^a			I _{DM}	220		
Linear Derating Factor				0.32	W/°C	
Single Pulse Avalanche Energy ^b			E _{AS}	100	mJ	
Maximum Power Dissipation	T _C =	25 °C	P _D 52		W	
Peak Diode Recovery dV/dt ^c			dV/dt	4.5	V/ns	
Operating Junction and Storage Temperature Range			T _J , T _{stg}	- 55 to + 175	°C	
Soldering Recommendations (Peak Temperature)	for 10 s			300 ^d		
Mounting Torque	6.22 or 1	6-32 or M3 screw		10	lbf ⋅ in	
	0-32 OF WIS SCIEW			1.1	N · m	

Notes

a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).

b. $V_{DD} = 25 \text{ V}$, starting $T_J = 25 \text{ °C}$, $L = 129 \text{ }\mu\text{H}$, $R_G = 25 \Omega$, $I_{AS} = 30 \text{ A}$ (see fig. 12). c. $I_{SD} \leq 52 \text{ A}$, dI/dt $\leq 250 \text{ A}/\mu\text{s}$, $V_{DD} \leq V_{DS}$, $T_J \leq 175 \text{ °C}$.

d. 1.6 mm from case.

THERMAL RESISTANCE RAT	TINGS							
PARAMETER	SYMBOL	TYP	-	MAX.		UNIT		
Maximum Junction-to-Ambient	R _{thJA}	- 65			0000			
Maximum Junction-to-Case (Drain)	R _{thJC}	- 3.1				°C/W		
SPECIFICATIONS $T_J = 25 \ ^{\circ}C$,	unless otherw	vise noted						
PARAMETER	SYMBOL	TES	T CONDITI	ONS	MIN.	TYP.	MAX.	UNIT
Static								
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} =	= 0 V, I _D = 2	50 µA	60	-	-	V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Referenc	e to 25 °C,	I _D = 1 mA	-	0.060	-	V/°C
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} =	V_{GS} , $I_D = 2$	250 μΑ	1.0	-	3.0	V
Gate-Source Leakage	I _{GSS}	V _{GS} = ± 20 V			-	-	± 100	nA
Zara Gata Valtaga Drain Current	I	V _{DS} =	= 60 V, V _{GS}	= 0 V	-	-	25	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 48 V,	V _{DS} = 48 V, V _{GS} = 0 V, T _J = 150 °C			-	250	μA
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} = 10 V	I _D	= 18 A ^b	-	0.027	-	Ω
Forward Transconductance	g _{fs}	V _{DS} =	= 25 V, I _D =	18 A ^b	15	-	-	S
Dynamic		•				-		
Input Capacitance	C _{iss}	$V_{GS} = 0 V,$ $V_{DS} = 25 V,$ f = 1.0 MHz, see fig. 5 f = 1.0 MHz			-	1500	-	
Output Capacitance	C _{oss}			-	720	-	рF	
Reverse Transfer Capacitance	C _{rss}			-	100	-		
Drain to Sink Capacitance	С			-	12	-		
Total Gate Charge	Qg				-	-	95	nC
Gate-Source Charge	Q _{gs}	$V_{GS} = 10 V$		2 A, V _{DS} = 48 V, fig. 6 and 13 ^b	-	-	27	
Gate-Drain Charge	Q _{gd}		000 1		-	-	46	
Turn-On Delay Time	t _{d(on)}				-	19	-	
Rise Time	t _r	$\begin{array}{l} V_{DD} = 30 \; V, \; I_D = 52 \; A, \\ R_G = 9.1 \; \Omega, \; R_D = 0.54 \; \Omega, \\ & \text{see fig. } 10^b \end{array}$		-	120	-	ns	
Turn-Off Delay Time	t _{d(off)}			-	55	-		
Fall Time	t _f			-	86	-		
Internal Drain Inductance	L _D	Between lead, 6 mm (0.25") from package and center of die contact		-	4.5	-	nH	
Internal Source Inductance	L _S			-	7.5	-		
Drain-Source Body Diode Characteristic	s	•				-		
Continuous Source-Drain Diode Current	I _S	MOSFET symbol showing the		-	-	45	A	
Pulsed Diode Forward Currenta	I _{SM}	integral reverse p - n junction diode			-	-		120
Body Diode Voltage	V_{SD}	$T_J=25~^{\circ}C,~I_S=30~A,~V_{GS}=0~V^b$		-	-	2.5	V	
Body Diode Reverse Recovery Time	t _{rr}	T _J = 25 °C, I _F = 52 A, dl/dt = 100 A/μs ^b		-	140	300	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	$r_{\rm J} = 23$ C, $r_{\rm F} = 32$ A, u/u = 100 A/µs ³			-	1.2	2.8	μC
Forward Turn-On Time	t _{on}	Intrinsic tu	rn-on time i	s negligible (turn	-on is dor	ninated by	/ L _S and I	_D)

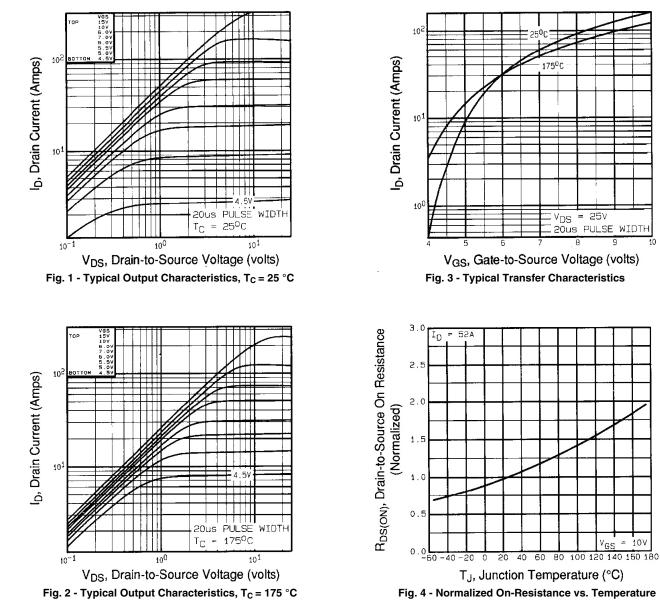
Notes

a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11). b. Pulse width \leq 300 µs; duty cycle \leq 2 %.



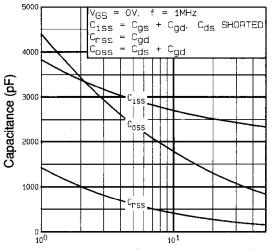
10

10V



TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted





V_{DS}, Drain-to-Source Voltage (volts) Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

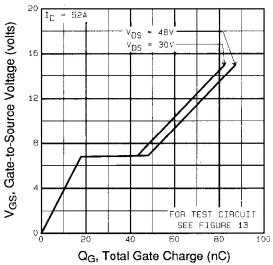


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

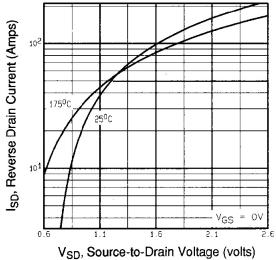
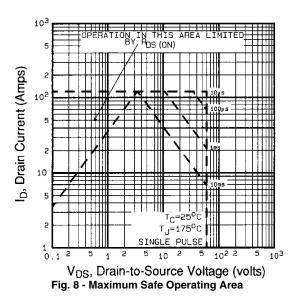


Fig. 7 - Typical Source-Drain Diode Forward Voltage



2SK2385



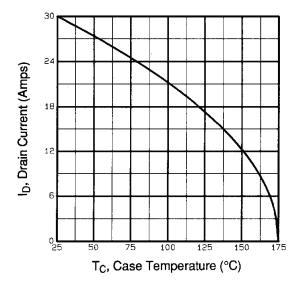


Fig. 9 - Maximum Drain Current vs. Case Temperature

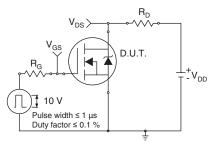


Fig. 10a - Switching Time Test Circuit

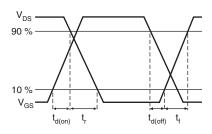


Fig. 10b - Switching Time Waveforms

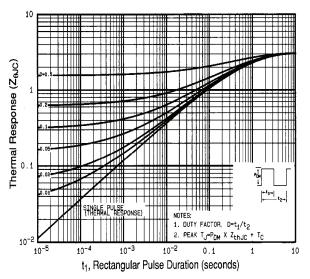


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

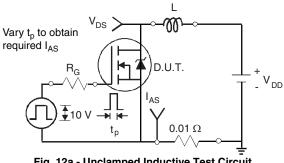


Fig. 12a - Unclamped Inductive Test Circuit

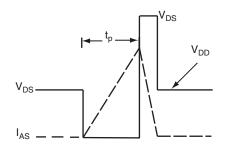
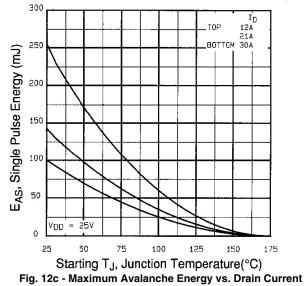


Fig. 12b - Unclamped Inductive Waveforms







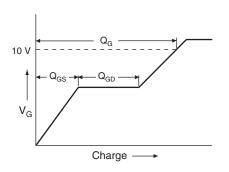
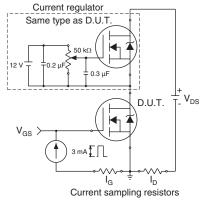
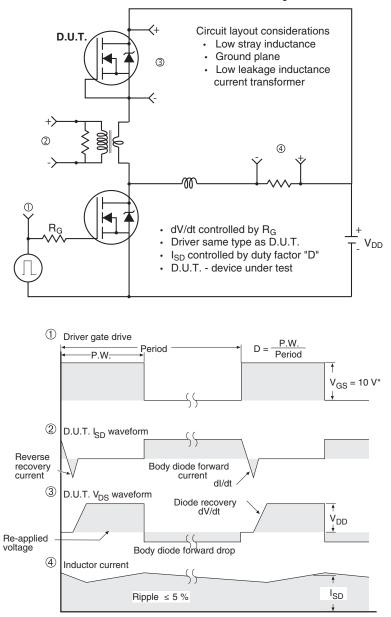


Fig. 13a - Basic Gate Charge Waveform









Peak Diode Recovery dV/dt Test Circuit

* V_{GS} = 5 V for logic level devices

Fig. 14 - For N-Channel



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